

Low melting point solder paste

TB48-M742 Sn 58.0Bi



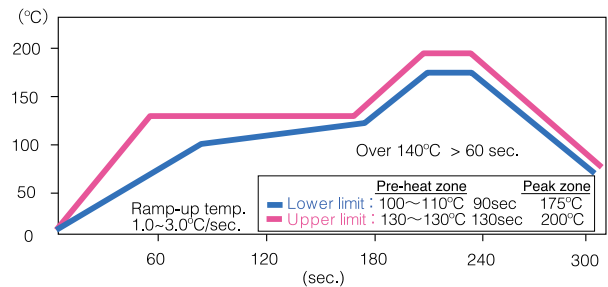
Combines reliability and workability with low temperature reflow

Reduces damage to components, boards, and cost by low temperature reflow

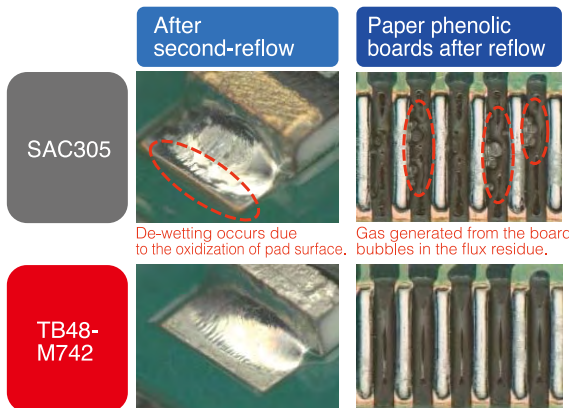
TB48-M742, a low melting point alloy (138°C), brings the following benefits associated with low temperature reflow;

1. Available with temperature sensitive materials
2. Less heat damage to components given by double sided reflow
3. Reduction of running costs by saving electricity consumption.

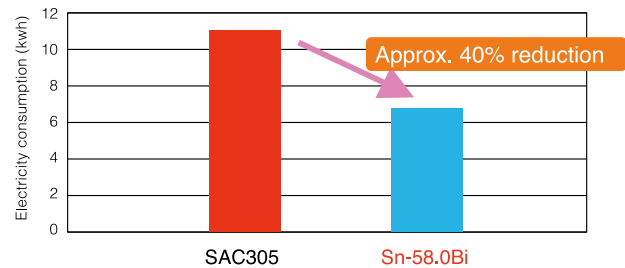
■ TB48-M742 Recommended reflow profile



■ Figure 1. Comparison of PCB's condition after reflow



■ Figure 2. Electricity consumption / hr during reflow process



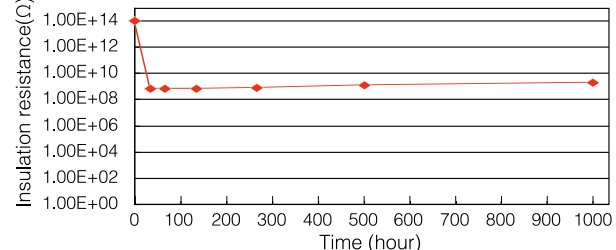
TB48-M742 enables a saving of approx. 40% reduction in running cost by low temperature reflow.

High electrical reliability

Optimized flux and solvent formulation of TB48-M742 realizes excellent compatibility between electrical reliability and workability for low temperature reflow with sufficient SIR, printing idle time and tack time.

■ Figure 3. Voltage applied SIR

- Condition: 85±2°C x 85%RH for 1000hrs
- Test piece: JIS type-II ● Voltage applied: DC50V



Product specifications			SnBi type low MP alloy	
Product name	TB48-M742	T4AB58-M742	Low MP	Low energy
Alloy composition (%)	Sn 58.0Bi	Sn 57.6Bi 0.4Ag	Low voiding	Halogen free
Melting point (°C)	138	138-140	Fine pitch printing >0.4mm pitch >0.3mm dia. CSP	Tack time >16h
Particle size (µm)	20-45	20-38	No clean type	No-clean
Viscosity (Pa.s)		190		
Flux content (%)		10.0		
Halide content (%)		0		
Flux type		ROLO		